



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

August 8, 2007

Applicants: Uwe HOFMANN et al

For: LEAD-FREE COPPER ALLOY AND A METHOD OF MANUFACTURE

Serial No.: 10/786 470 Group: 1742

Confirmation No.: 9330

Filed: February 25, 2004 Examiner: Ip

Atty. Docket No.: 5200.P0062US

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

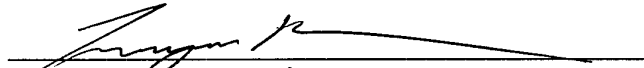
Sir:

In response to the Office Action dated April 19, 2007,
please amend the above-identified application as follows:

(Please see following pages.)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service with
sufficient postage as first class mail in an envelope
addressed to: Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450, on August 8, 2007.


Terryence F. Chapman